



Material Content Data Sheet



Sales Product Name		BC 848BW H6327		Issued		25. September 2017		
MA#		MA000854912						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		5	
	noble metal	gold	7440-57-5	0.003	0.05		493	
	inorganic material	silicon	7440-21-3	0.025	0.42	0.47	4207	4705
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1324	
	non noble metal	copper	7440-50-8	2.617	43.95	44.13	439446	441299
wire	non noble metal	copper	7440-50-8	0.006	0.10	0.10	973	973
encapsulation	organic material	carbon black	1333-86-4	0.032	0.53		5291	
	plastics	epoxy resin	-	0.677	11.37		113748	
	inorganic material	silicondioxide	60676-86-0	2.442	41.00	52.90	410020	529059
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22283	22283
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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